12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	**20260914001.1**	**PCN Issued**	September 14, 2026
Qualify additional Assembly site for select SOIC Package devices		**Sample request deadline:**	November 13, 2026
		Estimated 1st ship date:	December 13, 2026
***Sample requests received after** November 13, 2026* **will not be supported.**			

Change type(s)
Assembly Site Assembly Process Assembly Material Packing/Shipping/Labeling

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:

SOIC	
Assembly Sites	TIEMA, FMX, MLA, HFTF
Mount Compound	4147858 4211470 SID# A-03
Mold Compound	4211880 4230910 SID#R-30
Bond wire type	Cu, Au
Lead Finish	NiPdAu, Sn

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Request the Supporting Data Packet (SDP) for more details on the changes.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from	**Assembly Site Information**

this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TIEM	CU6	MYS	Melaka
FMX	MEX	MEX	Aguascalientes
MLA	MLA	MYS	Kuala Lumpur
HFTF	HFT	CHN	Hefei

Sample product shipping label (not actual product label):



Products Affected:

CD74HC86M96	TLC272IDR	LM339DR
LM239ADR	TLV9002IDR	LM358ADR
LM2904BAIDR	TLV9004IDR	LM358BAIDR
LM358LVIDR	TLV9022DR	LM358BIDR
LM393LVDR	TLV9052IDR	LM358DR
LMV339IDR	TLV9054IDR	NE5532ADR
LMV358AIDR	TLV9102IDR	NE5532DR
LMV358IDR	TLV9152IDR	RC4558DR
LMV393IDR	TLV9302IDR	RC4558DR.A
OPA2990IDR	TLV9352IDR	RC4580IDR
RC4558IDR	TMP1075DR	SN74ACT08DR
SN74AHC14DR	CD4066BM96	SN74ACT14DR
SN74HC86DR	LM239DR	SN74HCT08DR
SN74HCT14DR	LM258ADR	TL062CDR
TL062ACDR	LM258DR	TL062CDRE4
TL062ACDRG4	LM2901DR	TL062CDRG4
TLC272CDR	LM2904BIDR	TL062IDR
TLC272CDR.A	LM2904DR	TL3472IDR

SOIC Qualification Report

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	FMX TL494ID LT1013DD	TIEMA UCC21330BQDRQ1 TL084CDR ISO7763QDWRQ1
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	MLA MAX232D TCA9546ADR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0
AC	Autoclave 121C	96 hours	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0
MQ	Manufacturability	-	Pass

	Stress Test	Duration	HFTAT SN74HCS74D
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0
MQ	Manufacturability	-	Pass

Devices TL494ID, SN74HCS74D, MAX232D, ISO7221CD, LM6172IM/NOPB, TL084CDR, LT1013DD, TCA9546ADR are qualified at MSL1, 260C;
ISO7763QDWRQ1 qualified at MSL2, 260C; UCC21330BQDRQ1 qualified at MSL3, 260C.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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